

L Number	Hits	Search Text	DB	Time stamp
1	5	device and mounting near substrate and pressing and mounting adj pads and project\$3 near electrodes	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 11:03
2	20	Murakami near Tomoo .inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 11:03
-	0	device and substrate and mounting and pressing and deforming and sealling and 29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 10:57
-	644	device and substrate and mounting and pressing and 29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 10:57
-	4	device and substrate and mounting and pressing and 29/\$.ccls. and mounting adj pads and project\$3 near electrodes	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 10:59
-	4	device and substrate and mounting and pressing and (74/260, 174/256 , 174/261 , 257/E21.503 , 257/E21.511 , 257/E23.021 , 29/831 , 29/832 , 29/840).ccls. and mounting adj pads and project\$3 near electrodes	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 11:01
-	4	device and substrate and mounting and pressing and (29/830; 29/832 ; 29/836 ; 29/840 ; 29/739 ; 29/841 ; 29/838 ; 29/839 ; 29/837 ; 228/180.22 ; 257/772 ; 257/773 ; 257/775 ; 257/737 ; 257/778 ; 361/768 ; 361/773 ; 361/774 ; 174/260).ccls. and mounting adj pads and project\$3 near electrodes	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 11:01

	Title	Current OR
1	Image recording material and lithographic printing plate precursor	430/270.1
2	Method for mounting flip chip on circuit board through reliable electrical connections at low contact resistance	438/108
3	Method of mounting a semiconductor device to a substrate and a mounted structure	29/840
4	METHOD OF MOUNTING A SEMICONDUCTOR DEVICE TO A SUBSTRATE AND A MOUNTED STRUCTURE	174/260
5	Mounting method and apparatus of bare chips	438/113
6	Semiconductor device and semiconductor device mounting method thereof	257/684
7	Method for mounting flip chip on circuit board through reliable electrical connections at low contact resistance	438/108

	Current XRef
1	430/302
2	257/E21.503; 257/E21.508
3	174/250; 174/260; 174/263; 257/E21.503; 257/E21.511; 257/E23.021; 29/854
4	174/256; 174/261; 257/E21.503; 257/E21.511; 257/E23.021; 29/831; 29/832; 29/840
5	257/E21.503; 257/E21.508; 257/E21.514
6	257/737; 257/E21.503; 438/612; 438/615
7	228/180.22; 257/778; 257/E21.503; 257/E21.508; 438/127; 438/666

	Title	Current OR
8	Method of mounting a semiconductor device to a substrate	29/840
9	Flip chip mounting method and apparatus therefor	29/840
10	Semiconductor element mounting method	438/108
11	Method for producing a semiconductor device	438/108

	Title	Current OR
12	Method for manufacturing wiring pattern board	427/96
13	Method of mounting a semiconductor device to a substrate and a mounted structure	257/775
14	Method for manufacturing a printed circuit board having electrodes on end surface of substrate	29/852
15	Method for manufacturing printed circuit board with through-hole	29/852
16	Method of and apparatus for plating printed circuit board	427/98

	Title	Current OR
17	Fabrication method of printed wiring board	427/510
18	Silver halide photographic material containing a silica containing overlayer and specific hydrazine derivatives	430/264
19	CONNECTION STRUCTURE BETWEEN PRINTED BOARDS	
20	Image recording material and lithographic printing plate precursor	

	Title	Current OR
1	Method of mounting a semiconductor device to a substrate and a mounted structure	29/840
2	METHOD OF MOUNTING A SEMICONDUCTOR DEVICE TO A SUBSTRATE AND A MOUNTED STRUCTURE	174/260
3	Method of mounting a semiconductor device to a substrate	29/840

	Current XRef
1	174/250; 174/260; 174/263; 257/E21.503; 257/E21.511; 257/E23.021; 29/854
2	174/256; 174/261; 257/E21.503; 257/E21.511; 257/E23.021; 29/831; 29/832; 29/840
3	174/260; 257/738; 257/772; 257/773; 257/775; 257/778; 257/E21.503; 257/E21.511; 257/E23.021; 29/739; 29/832; 29/837; 29/841; 361/768; 361/773; 361/774